PT4800FE000F

Opaque Resin, Medium Directivity Angle, Thin Package Phototransistor

Features

- 1. Side view detection thin package
- 2. Plastic mold with opaque resin lens
- 3. Peak sensitivity wavelength: 860 nm (TYP.)
- 4. Medium directivity angle ($\Delta \theta \pm 35^{\circ}$ TYP.)
- 5. Lead free and RoHS directive compliant

■ Agency Approvals/Compliance

- 1. Compliant with RoHS directive (2002/95/EC)
- Content information about the six substances specified in "Management Methods for Control of Pollution Caused by Electronic Information Products Regulation" (popular name: China RoHS) (Chinese: 电子信息产品污染控制管理办法); refer to page 7.

Applications

- 1. Telecommunications equipment
- 2. Home Appliances
- 3. Office automation equipment
- 4. Audio visual equipment

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External Dimensions



■ Absolute Maximum Ratings

Ta = 25				
Parameter	Symbol	Rating	Unit	
Collector-emitter voltage	V _{CEO}	35	V	
Emitter-collector voltage	V _{ECO}	6	V	
Collector current	۱ _C	20	mA	
Collector power dissipation	P _C	75	mW	
Operating temperature	Topr	-25 to +85	°C	
Storage temperature	Tstg	-40 to +85	°C	
Soldering temperature *1	Tsol	260	°C	

*1 3 s (MAX.) at 1.8 mm from resin edge.

■ Electro-optical Characteristics

(Ta = 25°C)

Parameter	Symbol	Conditions *1	MIN.	TYP.	MAX.	Unit
Collector current	۱ _C	$Ee = 1 \text{ mW/cm}^2$, $V_{CE} = 5 \text{ V}$	0.08	0.25	0.75	mA
Dark current	I _{CEO}	Ee = 0, V _{CE} = 20 V	-	-	100	nA
Collector-emitter saturation voltage	V _{CE} (sat)	$Ee = 10 \text{ mW/cm}^2$, $I_C = 0.5 \text{ mA}$	-	-	0.4	V
Collector-emitter breakdown voltage	BV _{CEO}	I _C = 0.1 mA, Ee = 0	35	-	-	V
Emitter-collector breakdown voltage	BV _{ECO}	I _E = 0.01 mA, Ee = 0	6	-	-	V
Peak sensitivity wavelength	λρ	-	-	860	-	nm
Response time (Rise)	tr	$V_{CE} = 2 V, I_{C} = 2 mA,$	-	3.0	-	μs
Response time (Fall)	tf	R _L = 100 Ω	-	3.5	-	μs
Half intensity angle	θ	_	_	±35	-	degrees

*1 Ee: Irradiance by CIE standard light source A (tungsten lamp)

■ Collector Current Ranking

Rank	Collector Current Ic (mA)		
A	0.08 to 0.19		
В	0.15 to 0.38		
С	0.3 to 0.75		

*1 Quantities and ratios of any one ranking in any one shipment are at the discretion of Sharp.

Fig. 1 Collector Power Dissipation vs. Ambient Temperature







Fig. 3 Collector Dark Current vs. Ambient Temperature



Fig. 4 Relative Collector Current vs. Ambient Temperature



Fig. 5 Collector Current vs. Irradiance



Fig. 6 Collector Current vs. Collector-Emitter Voltage



Fig. 7 Response Time vs. Load Resistance



Fig. 8 Test Circuit for Response Time



Fig. 9 Sensitivity vs. Axis



Fig. 10 Collector-to-Emitter Saturation Voltage vs. Irradience



Fig. 11 Relative Output vs Distance



Distance between emitter and detector (mm)

Graph data is for reference only and is not guaranteed data.

Design Notes

1. This product is not designed to resist electromagnetic and ionized-particle radiation.

Manufacturing Guidelines

• Soldering Instructions

- 1. Sharp does not recommend soldering this part using preheat or solder reflow methods. Leads on this part are pre-coated with lead-free solder.
- 2. If hand soldering, use temperatures \leq 260°C for \leq 3 seconds.
- 3. When mounting this device, care should be taken to prevent any boundary exfoliation (pad lifting) between the solder, the pad, and the circuit board.
- 4. Do not subject the package to excessive mechanical force during soldering as it may cause deformation or defects in plated connections. Internal connections may be severed due to mechanical force placed on the package due to the PCB flexing during the soldering process.

Cleaning Instructions

- 1. Confirm this device's resistance to process chemicals before use, as certain process chemicals may affect the optical characteristics.
- 2. Solvent cleaning: Solvent temperature should be 45°C or below. Immersion time should be 3 minutes or less.
- 3. Ultrasonic cleaning: The effect upon devices varies due to cleaning bath size, ultrasonic power output, cleaning time, PCB size and device mounting circumstances. Sharp recommends testing using actual production conditions to confirm the harmlessness of the ultrasonic cleaning methods.
- 4. Recommended solvent materials: Ethyl alcohol, Methyl alcohol, and Isopropyl alcohol.

■ Presence of ODCs (RoHS Compliance)

This product shall not contain the following materials, and they are not used in the production process for this product:

• Regulated substances: CFCs, Halon, Carbon tetrachloride, 1,1,1-Trichloroethane (Methylchloroform). Specific brominated flame retardants such as the PBBOs and PBBs are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

- Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).
- Content information about the six substances specified in "Management Methods for Control of Pollution Caused by Electronic Information Products Regulation" (Chinese: 电子信息产品污染控制管理办法)

	Toxic and Hazdardous Substances					
Category	Lead (Pb)	mercury (Hg)	Cadmium (Cd)	Hexavalent chromiun (Cr ⁶⁺)	Polybrominated biphenyls (PBB)	Polybrominated diphenyl ethers (PBDE)
Photo Transistor	1	1	1	1	1	1

NOTE: \checkmark indicates that the content of the toxic and hazardous substance in all the homogeneous materials of the part is below the concentration limit requirement as described in SJ/T 11363-2006 standard.

Packing Specifications

- 1. Parts are packed in a plastic zipper bag, with 1000 pieces per bag.
- 2. Bags are secured in a box as shown in Figure 12.
- 3. Product mass: 0.07 g (approximately)

Fig. 12 Packing Composition



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(i) The devices in this publication are designed for use in general electronic equipment designs such as:

- --- Personal computers
- --- Office automation equipment
- --- Telecommunication equipment (terminal)
- --- Test and measurement equipment
- --- Industrial control
- --- Audio visual equipment
- --- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection with equipment that requires higher reliability such as:

- --- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- --- Traffic signals
- --- Gas leakage sensor breakers
- --- Alarm equipment
- --- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

- --- Space applications
- --- Telecommunication equipment (trunk lines)
- --- Nuclear power control equipment
- --- Medical and other life support equipment (e.g. scuba)

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